ON Semiconductor®

Final Product/Process Change Notification

Document #:FPCN23322X
Issue Date:07 Apr 2021

Title of Change:	SOIC8 Assembly Transfer of the NB3U1548CDG and NB3U1548CDR2G from SPEL to ON Semiconductor
Proposed First Ship date:	14 Jul 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Nhel.Malonzo@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Affected products will be identified with date code from new assembly site.
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Carmona, Philippines	SPEL Semiconductor Limited

Description and Purpose:

Transfer assembly from SPEL to ON Semiconductor which includes change in Leadframe design, die attach material, mold material and bond wire diameter.

	Before Change Description	After Change Description
Lead Frame	SOIC8 95X130 Cu	SOIC8 256 U/S LEADFRAME
Die Attach	CRM1076NS	Ablestik ABP 8062T
Bond Wire	0.8 mil Au	1.0 mil Au
Mold Compound	G633	G700LS
Assembly Site	SPEL Semiconductor Limited	ON Semiconductor Carmona, Philippines

No package dimension change and no product performance change.

Reliability Data Summary:

QV DEVICE NAME: NB3U1548CDG
RMS: 60762, 72534 and 74640
PACKAGE: SOIC8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 120% nominal Vcc	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/239
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/264
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/238
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/747
PD	JESD22-B100 and B108			0/30
SD	JSTD002	Ta = 245C, 5 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NB3U1548CDR2G	NB3U1548CDG
NB3U1548CDG	NB3U1548CDG

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Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NB3U1548CDG		NB3U1548CDG	NA	